Silicon N Channel MOS FET High Speed Power Switching

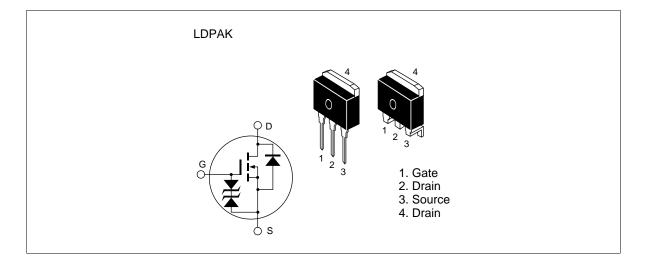
HITACHI

ADE-208-760A (Z) Target Specification 2nd. Edition Mar. 2001

Features

- Low on-resistance $R_{DS} = 40 \text{m}\Omega$ typ.
- · High speed switching
- 4V gate drive device can be driven from 5V source

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{ exttt{DSS}}$	150	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	30	A
Drain peak current	I _{D(pulse)} *1	120	A
Body-drain diode reverse drain current	I _{DR}	30	A
Avalanche current	_{AP} *3	30	A
Avalanche energy	E _{AR} *3	67	mJ
Channel dissipation	Pch*2	100	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

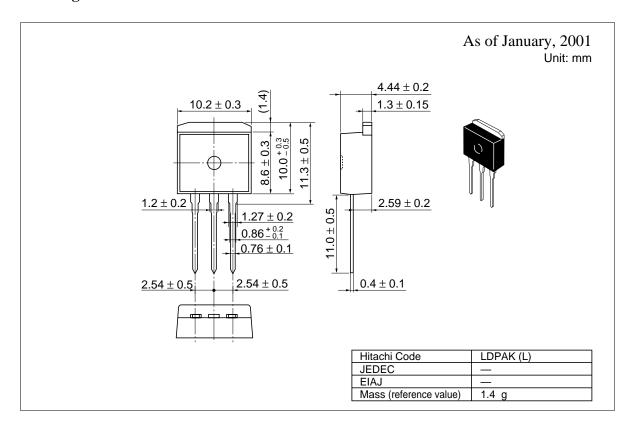
- Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %
 - 2. Value at Tc = 25°C
 - 3. Value at Tch = 25° C, Rg $\geq 50\Omega$

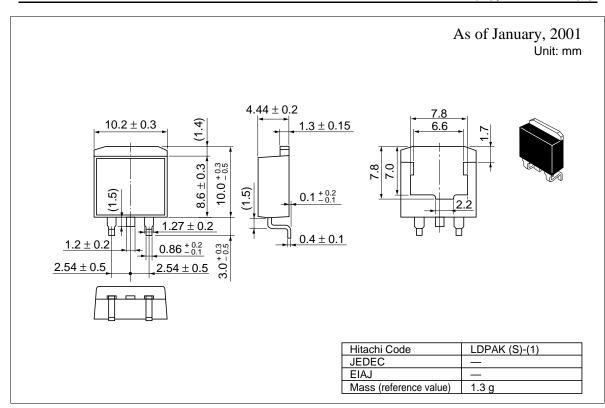
Electrical Characteristics ($Ta = 25^{\circ}C$)

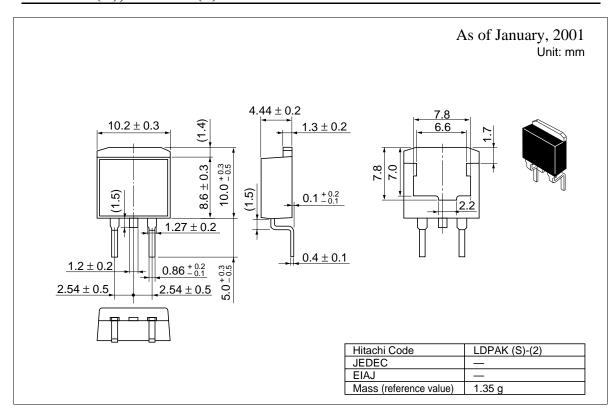
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	150	_	_	V	$I_{D} = 10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 150 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{mA}, V_{DS} = 10 \text{V}$
Static drain to source on state	$R_{\scriptscriptstyle DS(on)}$	_	40	45	$m\Omega$	$I_D = 15A, V_{GS} = 10V^{*4}$
resistance	R _{DS(on)}	_	45	63	$m\Omega$	$I_D = 15A, V_{GS} = 4V^{*4}$
Forward transfer admittance	$ y_{fs} $	18	30	_	S	$I_D = 15A, V_{DS} = 10V^{*4}$
Input capacitance	Ciss	_	2600	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	820	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	350	_	pF	f = 1MHz
Turn-on delay time	$t_{\text{d(on)}}$	_	25	_	ns	$I_D = 15A, V_{GS} = 10V$
Rise time	t _r	_	180	_	ns	$R_L = 2\Omega$
Turn-off delay time	$t_{\text{d(off)}}$	_	600	_	ns	
Fall time	t _f	_	280	_	ns	_
Body-drain diode forward voltage	V _{DF}	_	0.91	_	V	$I_F = 30A, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	110	_	ns	$I_F = 30A, V_{GS} = 0$ diF/ dt = 50A/ μ s

Note: 4. Pulse test

Package Dimensions







Cautions

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